

REMARKS

Claims 15, 17-19, 21-22, 34, 36-37 and 39-43 are in the application, with Claims 15, 19, 34 and 37 having been amended, and with claims 40-43 having been added. Claims 15, 19, 34 and 37 are the independent claims herein. No new matter has been added. Reconsideration and further examination are respectfully requested.

Claim Rejections – 35 USC § 103(a)

Claims 15, 17-18, 34 and 36 are rejected as being unpatentable over Murayama et al. U.S. Patent No. 6,548,330 (“Murayama”) in view of U.S. Patent No. 6,201,707 (“Sota”).

Claims 19, 21-22, 37 and 39 are rejected as being unpatentable over Murayama et al. in view of Sota further in view of Blumenau et al. U.S. Patent No. 6,421,711 (“Blumenau”).

To overcome the rejection of claim 15, the claim has been amended to recite the additional feature in each IC package of a ground plane formed on the opposite surface of the substrate from the surface on which the IC is mounted. Support for this amendment is found at page 3, lines 10-19 of the specification (ground plane 28, FIG. 1). It is believed that claim 15 is now allowable over the prior art references applied by the Examiner since those references do not teach or suggest a ground plane positioned as stated in claim 15. It is noted that the (apparently) metal feature 6 in the Murayama reference (see, e.g., FIG. 1 of the reference) is only an interconnection feature (column 4, lines 16-21) and does not constitute a ground plane. It is therefore respectfully requested that the rejection of claim 15 be reconsidered and withdrawn.

The other independent claims (19, 34, 37) have all been amended in like fashion to claim 15 and are submitted as patentable on the same basis as claim 15. The dependent claims are also submitted as patentable on the same basis.

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New claims 40-43 have been added, each dependent on a respective one of the independent claims. Each of the new claims adds the limitation of a solder mask layer to cover each ground plane recited in the parent claims. Support for this claim feature is found at page 3,

lines 21-26 of the specification (solder mask layer 34, FIG. 1). It is noted that this feature also is not taught or suggested by the prior art relied upon by the Examiner and is believed to provide an independent ground of patentability for the new claims 40-43.

CONCLUSION

Accordingly, Applicants respectfully request allowance of the pending claims. If any issues remain, or if the Examiner has any further suggestions for expediting allowance of the present application, the Examiner is kindly invited to contact the undersigned via telephone at (203) 972-3460.

Respectfully submitted,

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Nathaniel Levin
Registration No. 34,860
Buckley, Maschoff & Talwalkar LLC
Attorneys for Intel Corporation
Five Elm Street
New Canaan, CT 06840
(203) 972-3460